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| Title of Change: | NCV7240BDPR2G Metal Mask Revision. | |
| Proposed Changed Material First Ship Date: | 26 Dec 2020 or earlier if approved by customer | |
| Current Material Last Order Date: | 01 Oct 2020 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i> | |
| Current Material Last Delivery Date: | 25 Dec 2020 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i> | |
| Product Category: | Active components – Integrated circuits | |
| Contact information: | Contact your local ON Semiconductor Sales Office or Bill.Fontes@onsemi.com | |
| PCN Samples Contact: | Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. | |
| Sample Availability Date: | 01 Jan 2020 | |
| PPAP Availability Date: | 15 Feb 2020 | |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office or Youngchul.Lee@onsemi.com | |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com. | |
| Change Category | | |
| Category | Type of Change | |
| Design | Design Change in Routing | |
| Description and Purpose: | | |
| Width of metal runner in a key area of the die has been increased in order to improve the energy handling capability of the part. | | |
| No changes to design schematic. No effect on device parametric performance. | | |
| There are no product material changes as a result of this change. | | |
| There is no product marking change as a result of this change. | | |
| Reason / Motivation for Change: | Quality improvement | |
| Anticipated impact on fit, form, function, reliability, product safety or manufacturability: | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts. | |



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| Sites Affected: | | |
| ON Semiconductor Sites | | External Foundry/Subcon Sites |
| ON Semiconductor Gresham, Oregon | | None |
| Marking of Parts/ Traceability of Change: | date code | |
| Reliability Data Summary: No reliability testing required for this change. Characterization only. | | |
| Electrical Characteristics Summary: Electrical characteristics are not impacted. | | |
| List of Affected Part: <i>Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.</i> | | |
| Current Part Number | New Part Number | Qualification Vehicle |
| NCV7240BDPR2G | NA | NCV7240BDPR2G |